### SDGsに貢献するType4/5ソルダペースト! 35℃で3か月常温保管可能!

Type4&5 solder paste to contribute to the SDGs. Storage at 35 °C for 3 months is possible!

# NP303-C0SM0-LH-T4 NP303-C0SM0-LH-T5

#### 常温輸送、常温保管を可能に!

**Enables room temperature transport and storage!** 

#### 連続印刷ヌケ性良好!

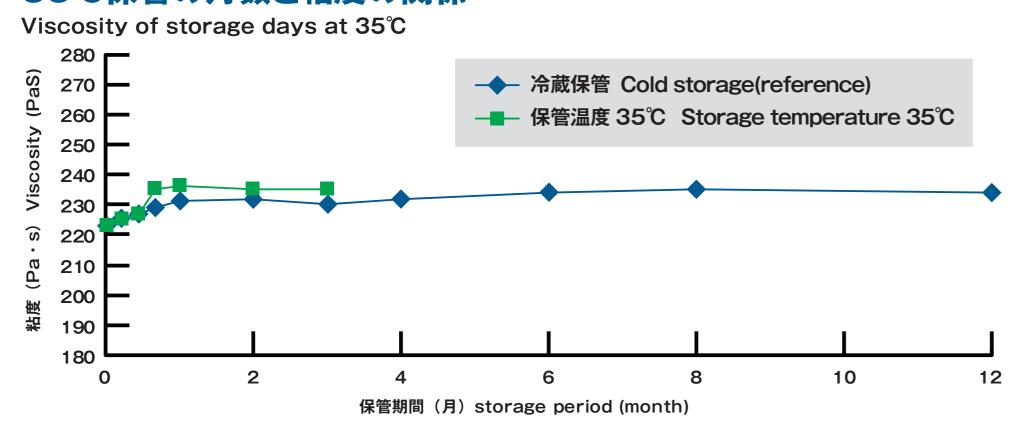
Continuous print suitability is good!

#### ROLO 対応! ROLO!

## 35℃で3ヶ月の常温保管が可能!

Possibly use after 3 month at 35°C storage

#### 35℃保管の月数と粘度の関係



# 冷蔵保管と同等で劣化なし!

Same quality as refrigerated storage

#### 35℃、3ヶ月保管後の状態

Status after storage at 35 °C for 3 months

	外観	印刷抜け(0402パターン)	溶融性 (0402 パターン)
	Appearance	Printability(0402 pattern)	Melting (0402 pattern)
35℃保管 (3ヶ月後) 35℃ storage (after 3months)			

# 連続印刷又ケ性良好!

Keep good printability at continuous printing

#### 連続印刷試験結果

Continuous printing test result

	1枚目 First printing	10枚目 10th printing	20枚目 20th printing
0402 pattern			
ФО.20mm dot			

## ヌレにくい部品でもヌレ性良好! Type4/5 ソルダペースト

Good wettability even with oxidized parts! Type4&5 solder paste

# NP303-GM855-T4-D NP303-GM855-T5-D

# Ni などのヌレにくい母材に対してもヌレ性良好!

Wettability to parts that are hard to get wet like Ni is also good!

### チップ横ボールの発生を激減!

Reduce the occurrence of chip side balls!

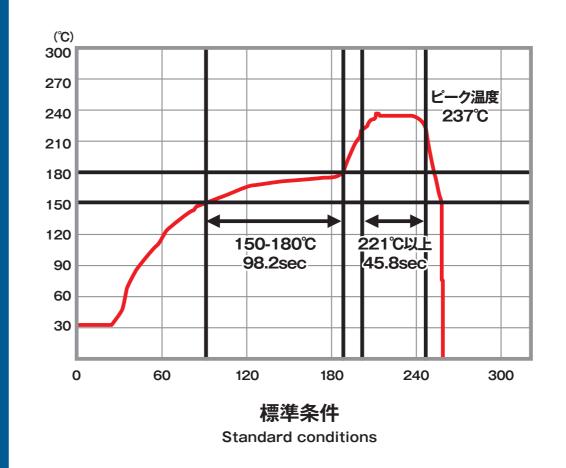
#### Niへのヌレ性良好!

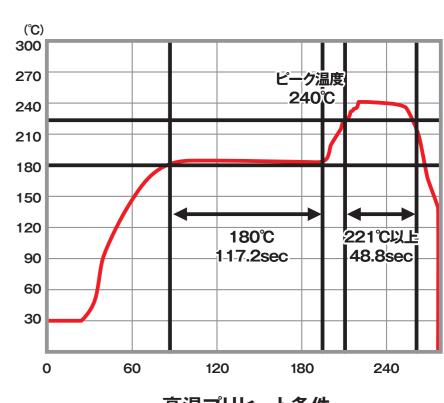
Good wettability to Ni!



メタルマスク開口部:Φ6.5mm, メタルマスク厚: 0.1mm Part of metal mask opening: \$\phi 6.5 mm\$, Metal mask thickness: 0.1 mm

加熱条件:下記リフロー条件を参照 Refer to the profile condition below





高温プリヒート条件 High temperature preheating condition

# チップ横ボール発生激減!

Reduce the occurrence of chip side balls!

	チップ横ボール数 (個) Number of chip side balls (Pieces)	
	標準条件 Standard conditions	高温プリヒート条件 High temperature preheating condition
従来品 Conventional product	63	97
NP303-GM855-T4-D	4	26

基板: 100×120×1.6mm 2125 部品搭載パターン(250点) Substrate:100×120×1.6mm 2125Component mounting pattern

メタルマスク厚: 0.2mm リフロー条件:上記リフロー条件を参照

Metal mask thickness:0.2mm

## QFPリード端面へのヌレ上がり良好!

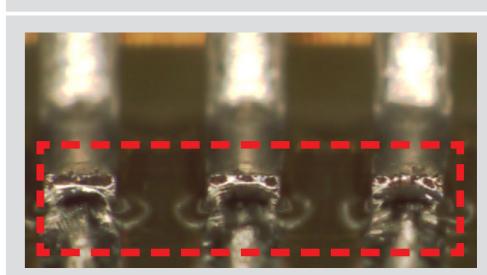
Please refer to the above profile condition

Excellent wettability to the end face of QFP lead





マスク厚: 0.15mm 部品: 0.65mm ピッチ QFP Part: 0.65 mm pitch QFP Mask thickness: 0.15 mm



NP303-GM855-T4-D

リフロー条件:上記リフロー条件を参照 Please refer to the above profile condition

